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forming a bond between a second surface of said mounting surface and an interior surface of said first sidewall; and

snapping said image sensor substrate along a singulation street between said first sidewall of said first substrate and a second sidewall of a second substrate of said image sensor substrate.--

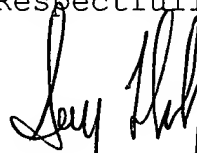
REMARKS

New Claims 26-30 have been added. Support for Claims 26-30 appears in the specification at least at page 2, line 9 to page 30, line 30 and in FIGS. 1-12B.

Claims 1-30 are pending in this application. If the Examiner has any questions relating to the above, the Examiner is respectfully requested to telephone the undersigned Attorney for Applicants.

EXPRESS MAIL LABEL NO:
EL579665754US

Respectfully submitted,



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